



A Product Line of  
Diodes Incorporated



## **SPECIFICATION FOR APPROVAL**

CUSTOMER \_\_\_\_\_

NOMINAL FREQUENCY \_\_\_\_\_ 8.000000 MHz

HOLDER TYPE TYPE FY 5.0x3.2 SEAM SEALED CRYSTAL

SPEC. NO. ( P/N ) FY0800057Q

CUSTOMER P/N \_\_\_\_\_

ISSUE DATE May 10, 2018

VERSION B

APPROVED	PREPARED	QA
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### Diodes Incorporated

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**\*Pb-free**  
**\*RoHS Compliant**  
**\*HF-Halogen Free**  
**\*REACH Compliant**  
**\*AEC-Q200 Compliant**

## TYPE FY 5.0x3.2 SEAM SEALED CRYSTAL

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VER. B 10-May-18

## VERSION HISTORY



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## ELECTRICAL SPECIFICATIONS

Item	Symbol	Specifications	Units	Notes
Nominal Frequency	Fn	8.000000	MHz	
Mode of Oscillation	MO	AT Cut-Fundamental		
Calibration Load Capacitance	CL	20	pF	
Calibration Tolerance	FL	$\pm 20$	ppm	at 25°C $\pm 3$ °C
Operating Temperature Range	TR	-40 to +125	°C	
Frequency Stability (Frequency Deviation over the Operating Temperature Range)	F/T	$\pm 50$	ppm	Reference to the Frequency at 25°C
Operating Drive Level		10	μW	
Maximum Drive Level		100	μW	
Equivalent Series Resistance	ESR	80	Ω	Max
Shunt Capacitance	C0	5	pF	Max
Aging at 25°C		$\pm 3$	ppm	Max, 1st year
Storage Temperature		-55 to +125	°C	
Insulation Resistance		500	MΩ	Min

※ This product doesn't include harmful substance that stipulated by SONY SS-00259 Level 1 and S-AT2-001 Level 1 standard. RoHS Compliant (Pb - Free).



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## AEC-Q200 RELIABILITY TEST SPECIFICATIONS:

### 1. Initial

- 1.1 Physical Dimensions: JESD22, Method JB1-100
- 1.2 External Visual: MIL-STD-883, Method 2009
- 1.3 Freq. Vs. Temperature: Per Specification/Datasheet

### 2. Mechanical

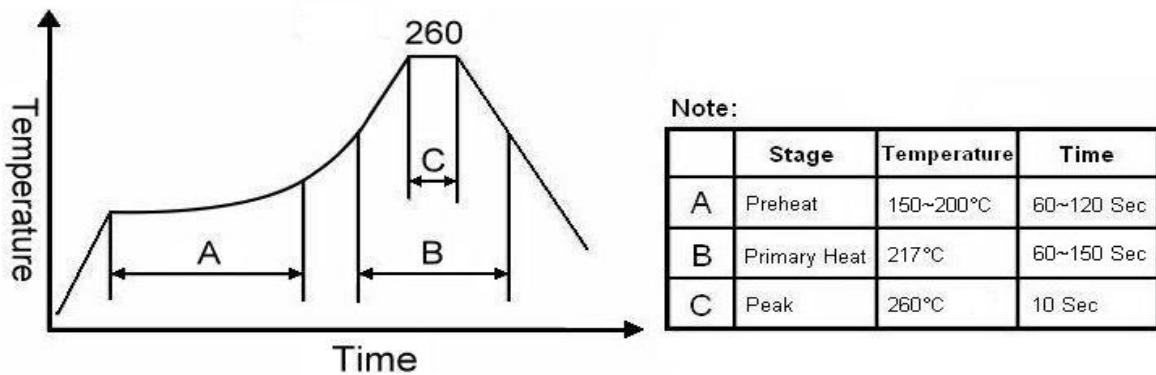
- 2.1 Mechanical Shock: MIL-STD-202 Method 213
- 2.2 Vibration: MIL-STD-202 Method 204
- 2.3 Solderability: J-STD-002
- 2.4 Board Flex: AEC Q200-005
- 2.5 Terminal Strength (SMD): AEC Q200-006

### 3. Environmental

- 3.1 Temp Cycle: JESD22, Method JA-104
- 3.2 Resistance to Solder Heat: MIL-STD-202 Method 210
- 3.3 High Temperature Operating Life: MIL-STD-202, Method 108
- 3.4 High Temp Exposure: MIL-STD-202, Method 108
- 3.5 High Temp & High Humidity: MIL-STD-202, Method 103
- 3.6 Thermal Shock: MIL-STD-202, Method 107

## SUGGESTED IR REFLOW PROFILE

\*As per IPC-JEDEC J-STD-020D



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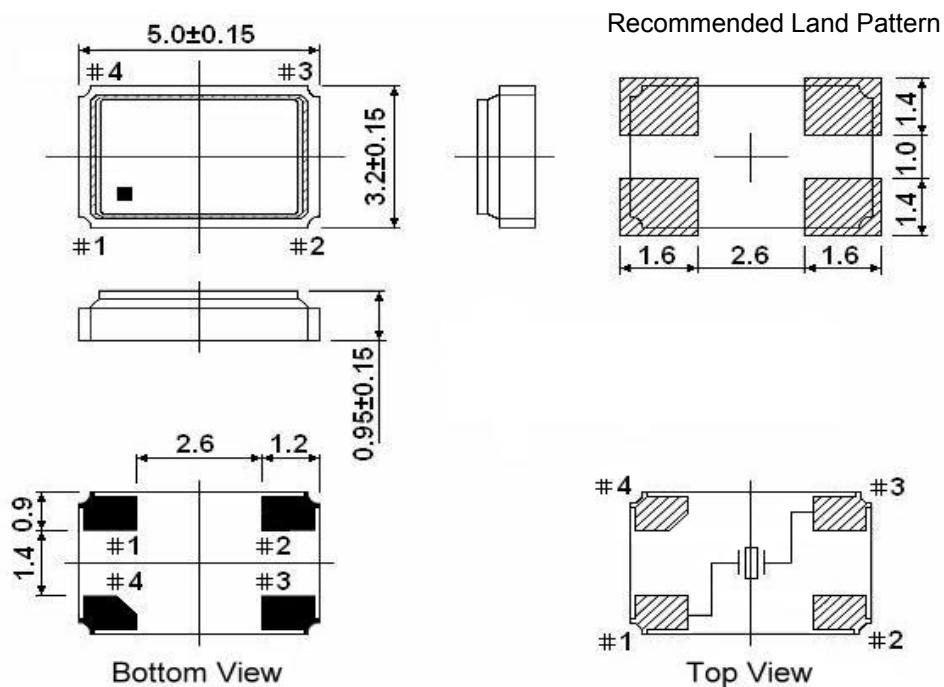
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VER. B 10-May-18

## MARKING



## MECHANICAL DRAWINGS ( Scale: None. Dimensions are in mm.)



\*\* Recommended - Pin 1 & 3 : CRYSTAL  
Pin 2 & 4 : GND

### Notes:

1. Package drawings are for reference only, and the appearances of objects may vary.  
Actual packages are based on the real product.
2. The marking dot denotes Pin#1.
3. The position and shape of the chamfer pin may vary and are based on the real product.

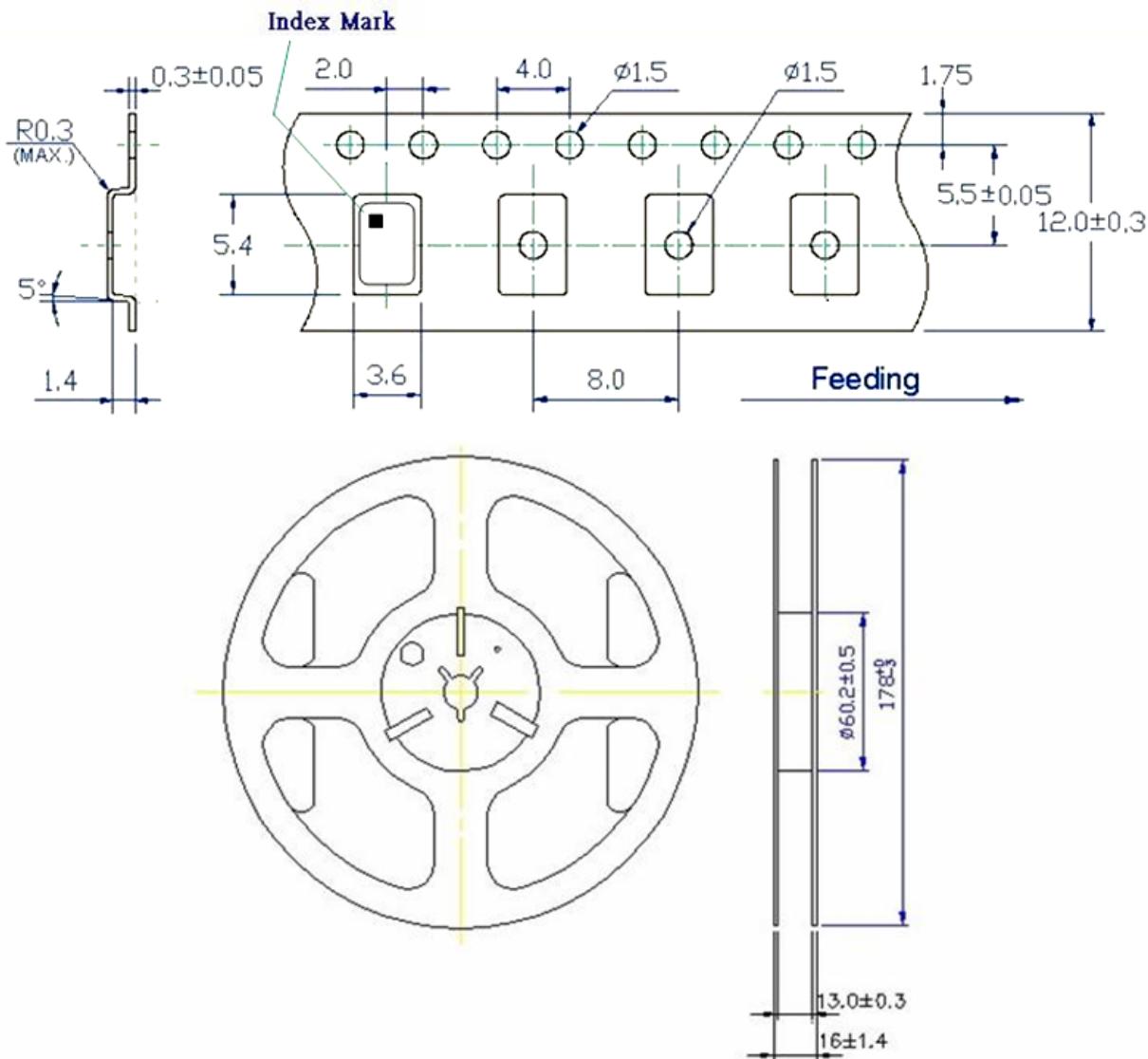
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## Tape & Reel



1. 230mm minimum leafer which consist of carrier and/or tape followed by a minimum of 160mm of empty carrier tape sealed with cover tape.
2. 160mm minimum trailer of empty carrier tape sealed with cover tape.

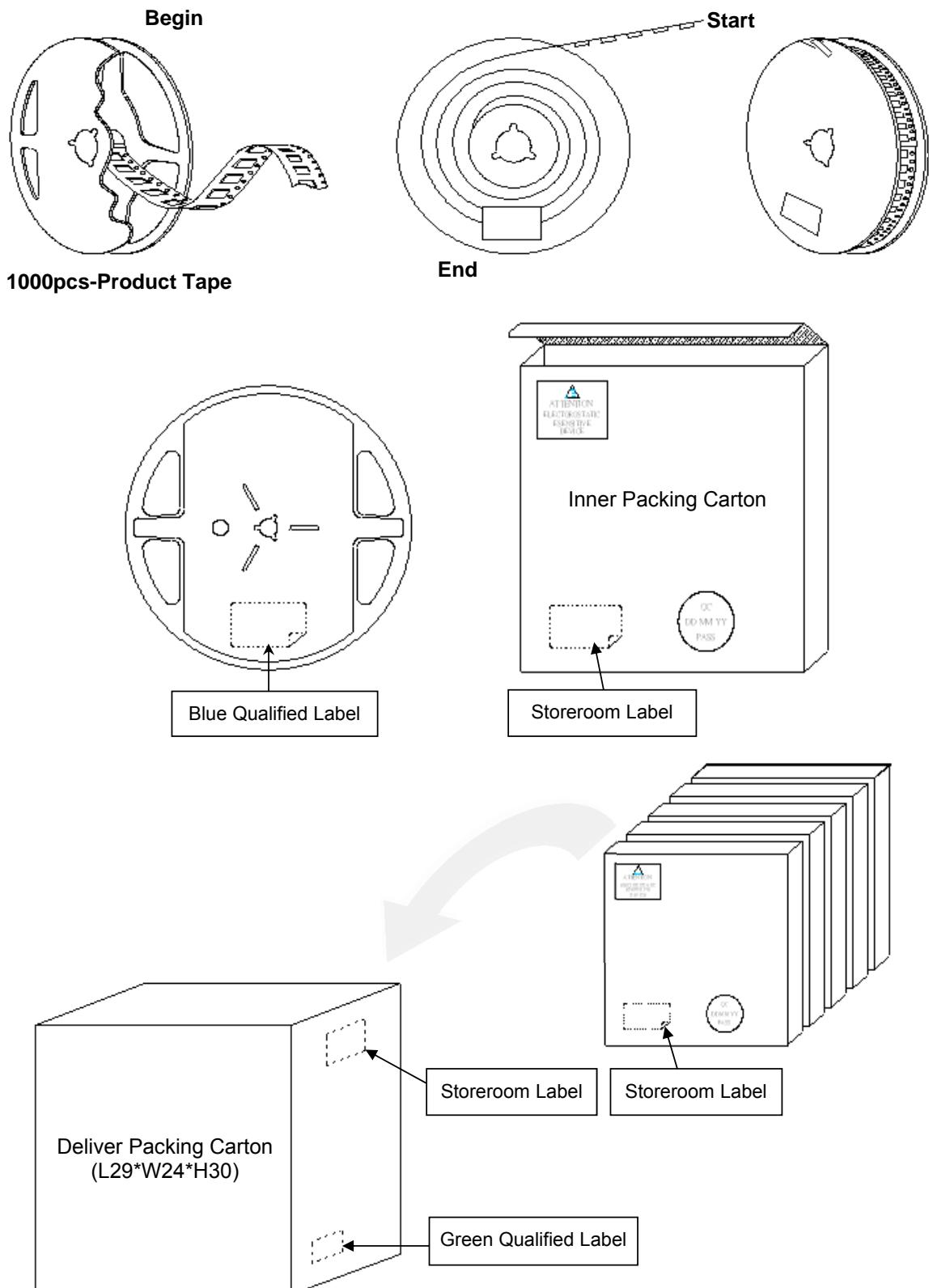
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## PACKING



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